

# HRW0302A

## Silicon Schottky Barrier Diode for Rectifying

REJ03G0156-0800Z  
(Previous: ADE-208-015G)  
Rev.8.00  
Dec.15.2003

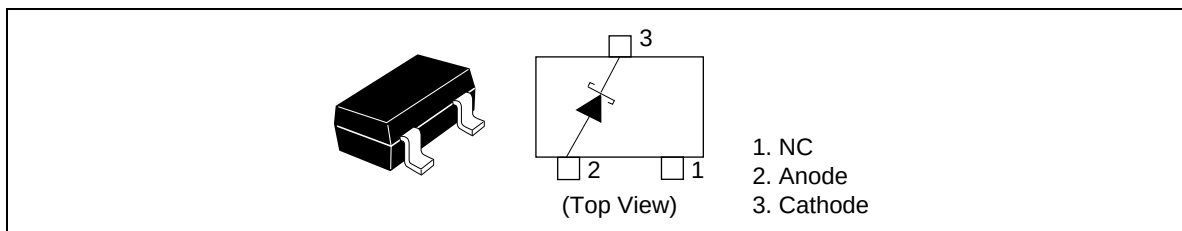
### Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- MPAK Package is suitable for high density surface mounting and high speed assembly.

### Ordering Information

| Type No. | Laser Mark | Package Code |
|----------|------------|--------------|
| HRW0302A | S11        | MPAK         |

### Pin Arrangement



## Absolute Maximum Ratings

(T<sub>a</sub> = 25°C)

| Item                                      | Symbol                          | Value       | Unit |
|-------------------------------------------|---------------------------------|-------------|------|
| Repetitive peak reverse voltage           | V <sub>RMM</sub> * <sup>1</sup> | 20          | V    |
| Average rectified current                 | I <sub>O</sub> * <sup>1</sup>   | 300         | mA   |
| Non-Repetitive peak forward surge current | I <sub>FSM</sub> * <sup>2</sup> | 3           | A    |
| Junction temperature                      | T <sub>J</sub>                  | 125         | °C   |
| Storage temperature                       | T <sub>stg</sub>                | -55 to +125 | °C   |

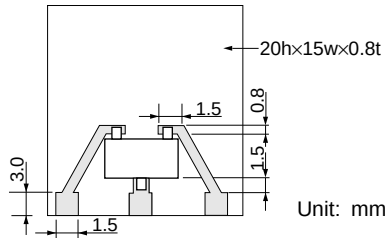
Notes: 1. See from Fig.4 to Fig.6  
2. 10ms sine wave 1 pulse

## Electrical Characteristics

(T<sub>a</sub> = 25°C)

| Item               | Symbol               | Min | Typ | Max  | Unit | Test Condition                  |
|--------------------|----------------------|-----|-----|------|------|---------------------------------|
| Forward voltage    | V <sub>F</sub>       | —   | —   | 0.40 | V    | I <sub>F</sub> = 300 mA         |
| Reverse current    | I <sub>R</sub>       | —   | —   | 100  | μA   | V <sub>R</sub> = 20 V           |
| Capacitance        | C                    | —   | —   | 100  | pF   | V <sub>R</sub> = 0 V, f = 1 MHz |
| Thermal resistance | R <sub>th(j-a)</sub> | —   | 340 | —    | °C/W | Polyimide board * <sup>1</sup>  |

Note: 1. Polyimide board



## Main Characteristic

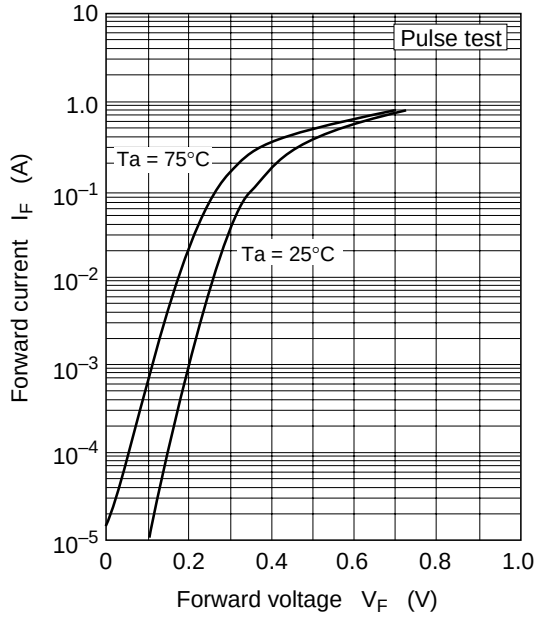


Fig.1 Forward current vs. Forward voltage

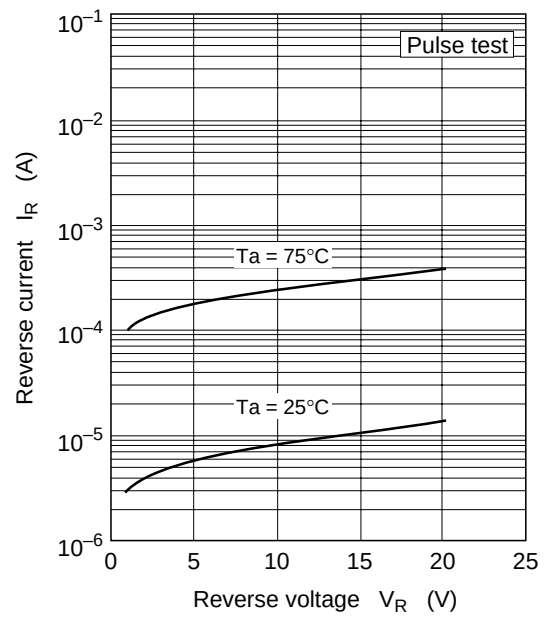


Fig.2 Reverse current vs. Reverse voltage

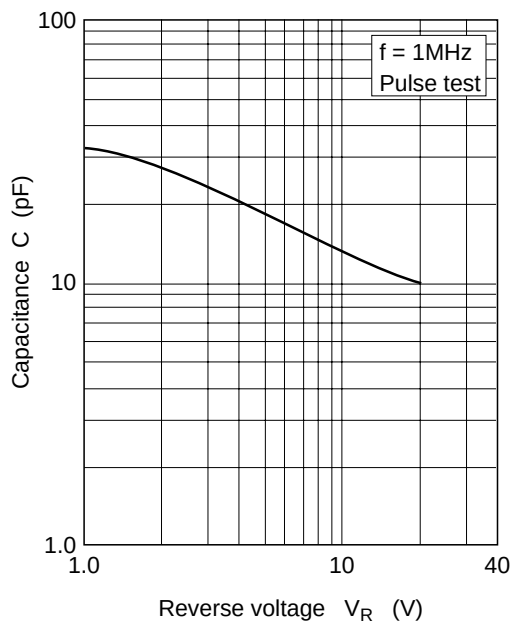


Fig.3 Capacitance vs. Reverse voltage

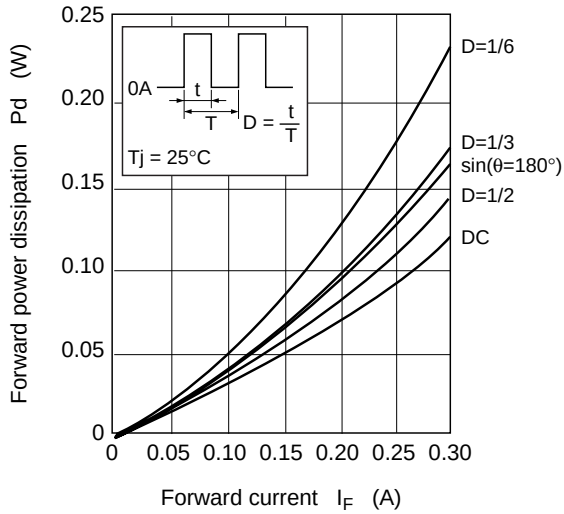


Fig.4 Forward power dissipation vs. Forward current

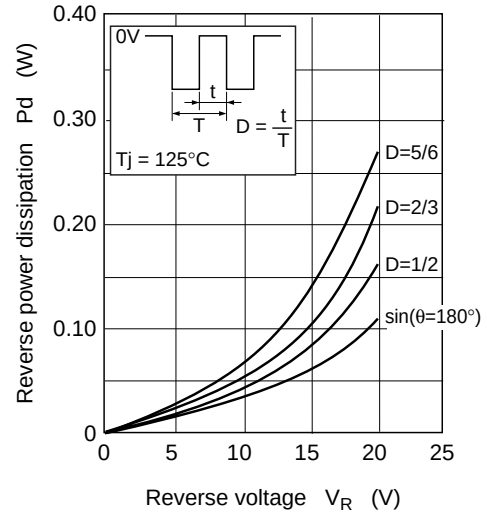


Fig.5 Reverse power dissipation vs. Reverse voltage

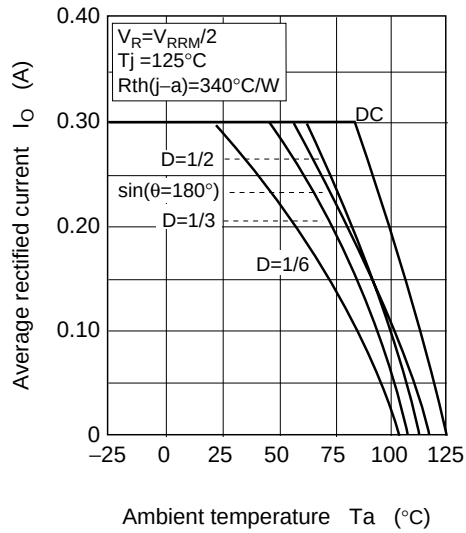
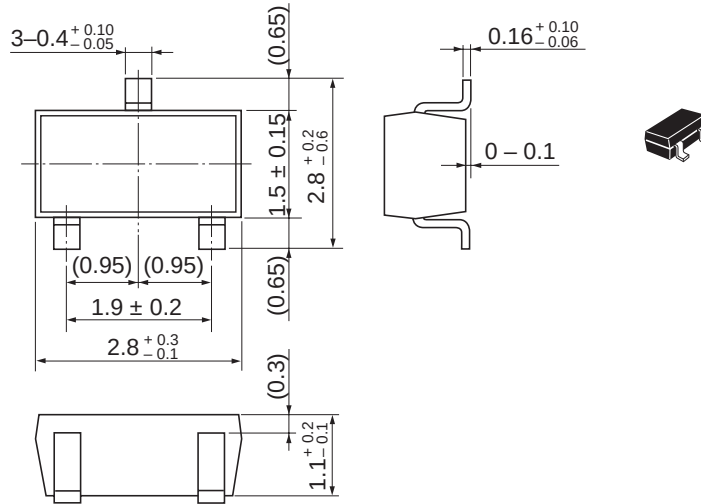


Fig.6 Average rectified current vs. Ambient temperature

## Package Dimensions

As of January, 2003

Unit: mm



|                        |          |
|------------------------|----------|
| Package Code           | MPAK     |
| JEDEC                  | —        |
| JEITA                  | Conforms |
| Mass (reference value) | 0.011 g  |

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